

LOC		DIST		REVISONS			
P	LTR	DESCRIPTION		DATE	DWN	APVD	
A		INITIAL RELEASE		18NOV2010	RC	CW	

- 1

MATERIAL:
CONTACT: PHOSPHOR BRONZE.
HOUSING: GLASS-FILLED POLYESTER.
- 2

GENERAL PLATING SPECIFICATION: UNDERPLATING
(ENTIRE CONTACT): 1.27μm MIN NICKEL AND ACTION
PIN: 0.5μm MIN TIN/LEAD.
1.27μm MIN GOLD PLATING ON MATING SURFACES
- 3

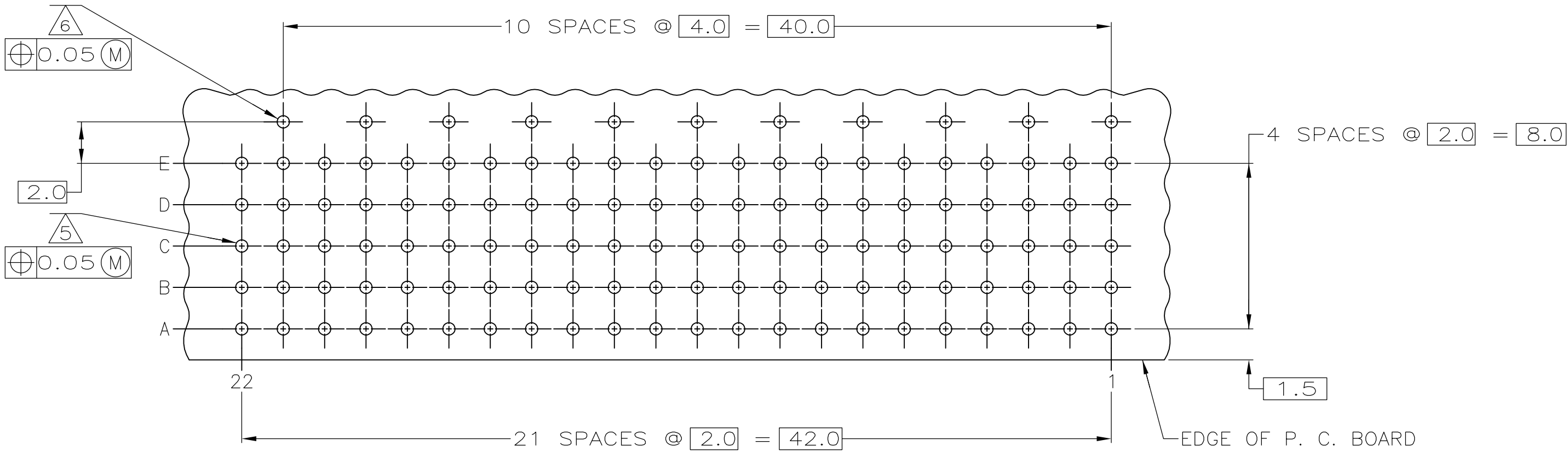
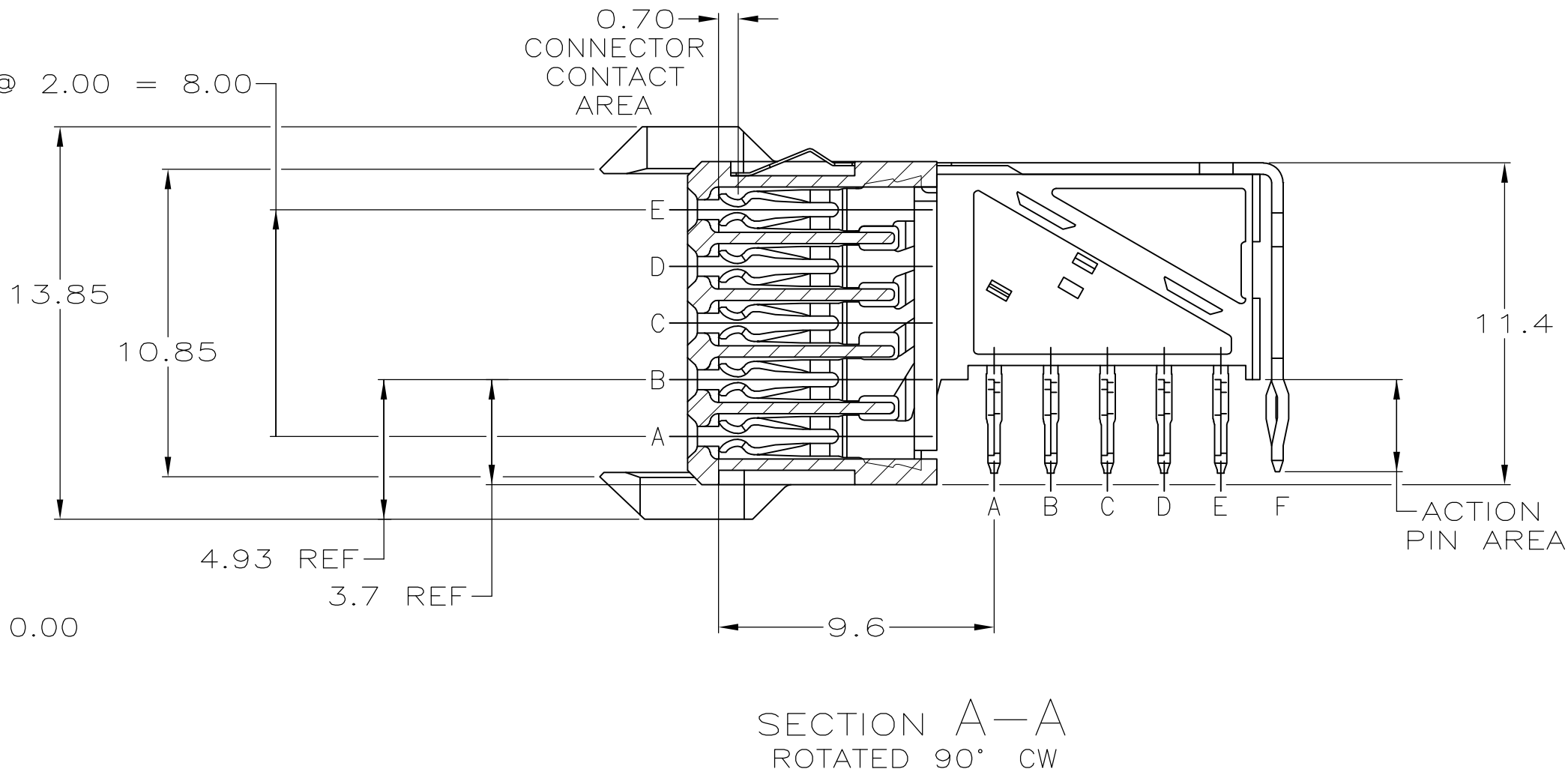
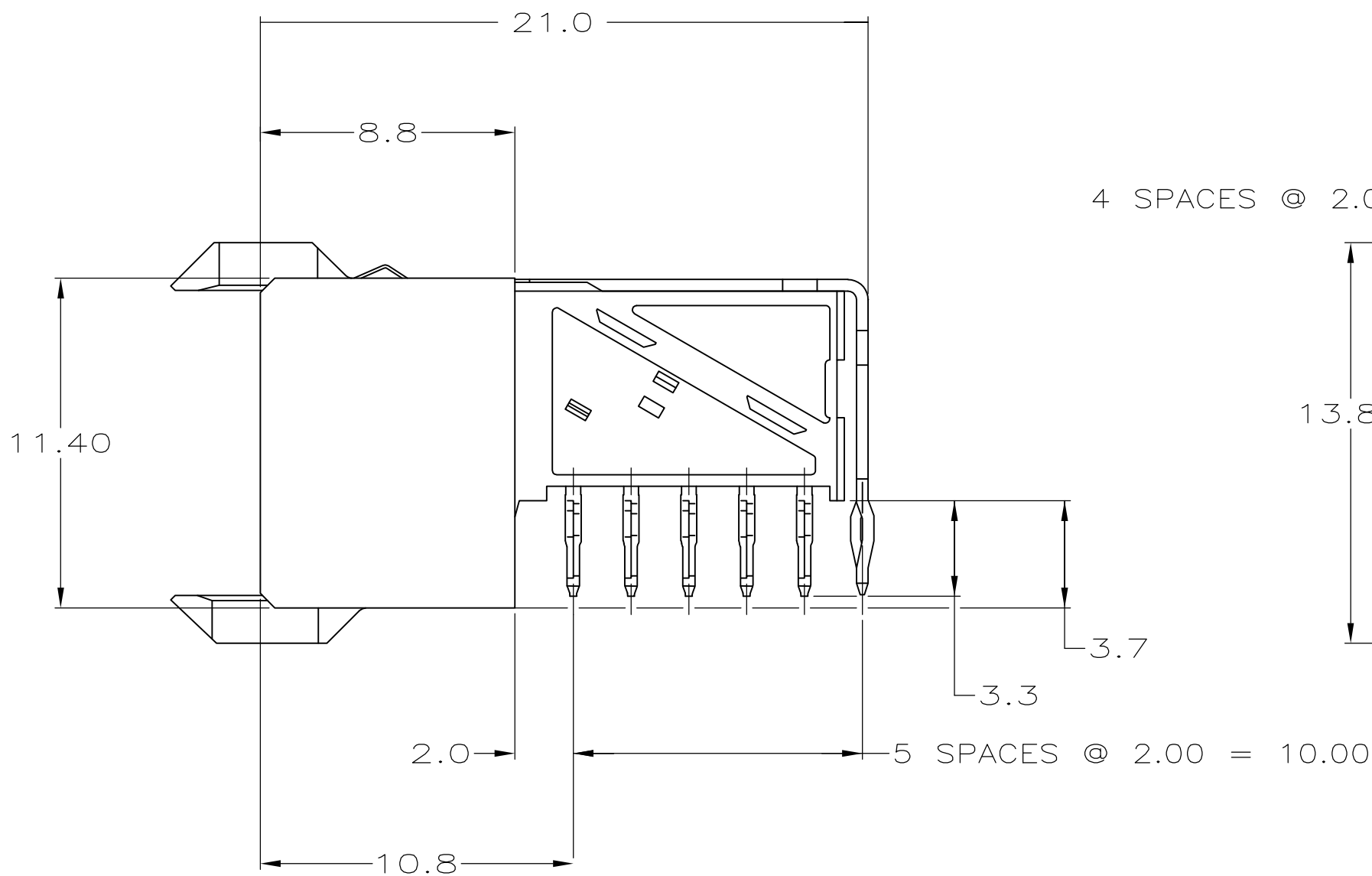
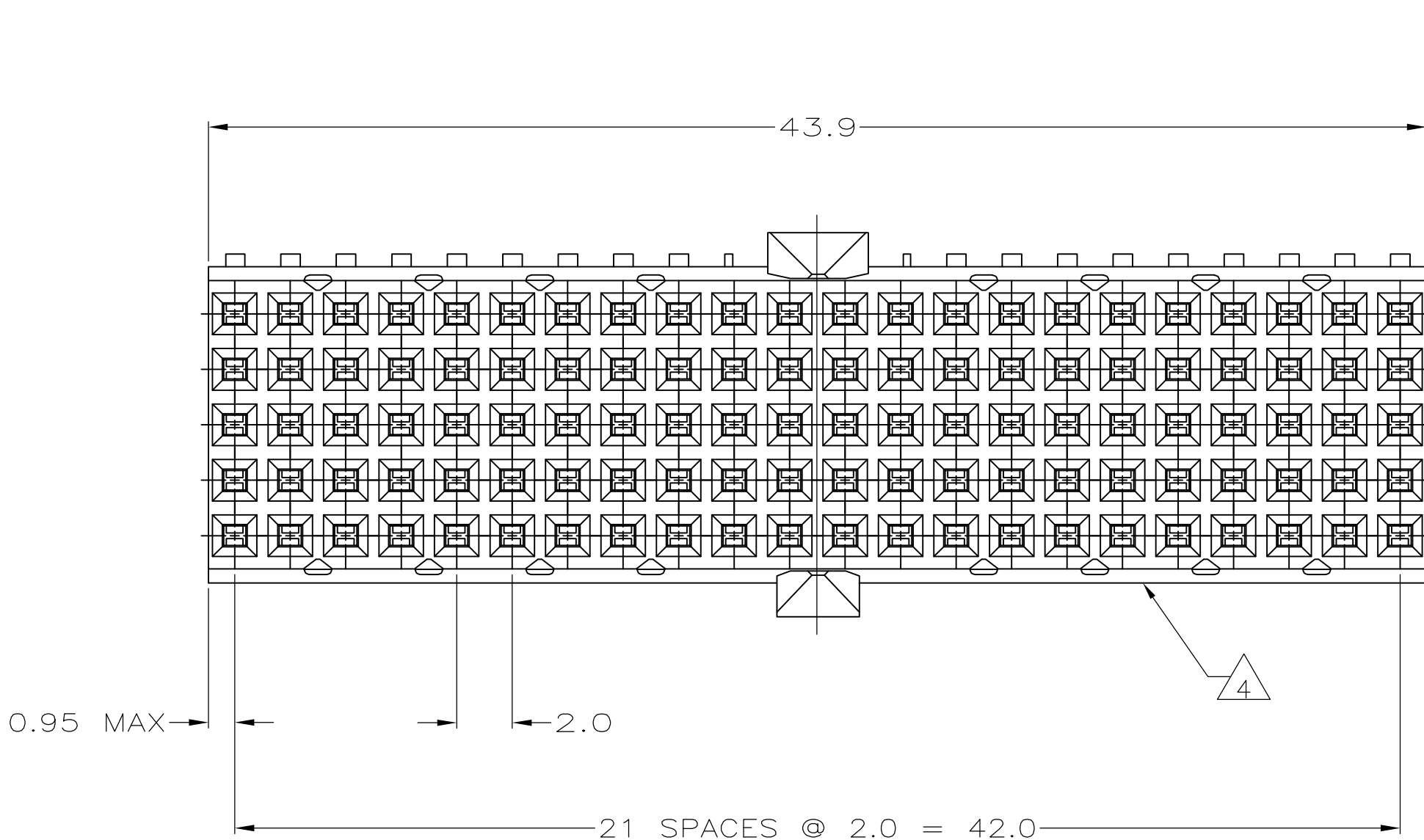
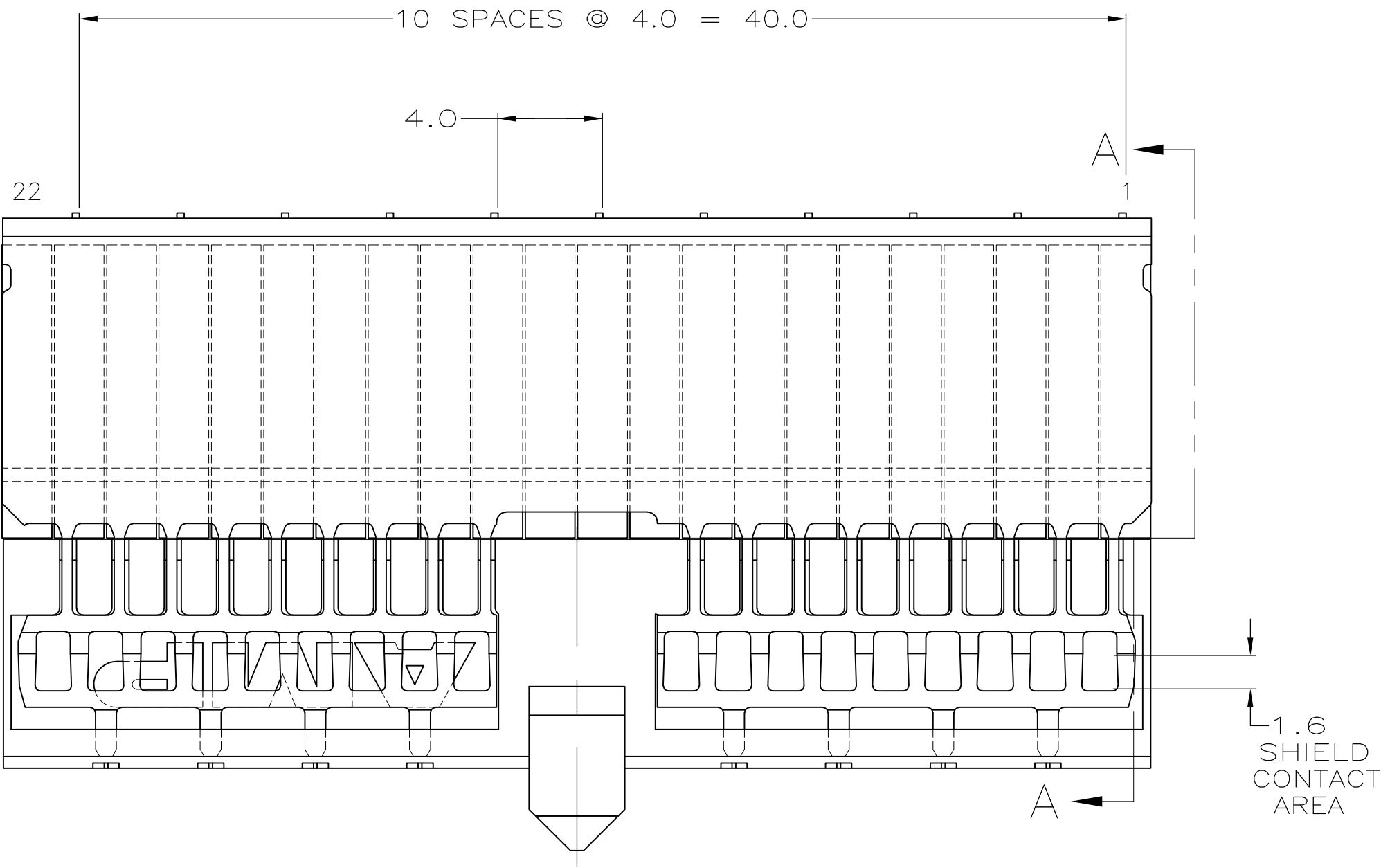
CONFORMS TO ALL TESTING ACCORDING TO IEC 61076-4-101
PERFORMANCE LEVEL 1.
- 4

CONNECTOR MARKED WITH PART NUMBER AND DATE CODE.
ADDITIONAL CHARACTERS OR MARKINGS, AS WELL AS THE LOCATION OF THE MARKINGS,
MAY BE ADDED FOR TRACEABILITY BASED UPON MANUFACTURERS DISCRETION.
- 5

PLATED-THROUGH HOLES AT 2x2mm SQUARE GRID
PATTERN DEFINED BY CONTACT LAYOUT.
- 6

10 PLATED THROUGH HOLES FOR UPPER SHIELD, ROW F.
- 7

SHIELD MOUNTED TO CONNECTOR WITH DOUBLE SIDED ADHESIVE TAPE OR ADHESIVE.



PLATED THRU HOLES PARAMETERS
REFERENCE APPLICATION SPECIFICATION

RECOMMENDED PCB-HOLE LAYOUT
COMPONENT SIDE SHOWN

SCALE 2.5:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN RAYMOND CAO 11/18/2010	Tyco Electronics Corporation	
		CHK SANDERS YAN 11/18/2010	Shanghai, P.R.China, 200233	
DIMENSIONS: mm		APVD MANQIAN WANG 11/18/2010	NAME RECEPTACLE ASSEMBLY,Z-PACK 2mm HM, TYPE A/B,PRESHIELDED,110 POSITION	
		PRODUCT SPEC	SIZE 108-19082	
		APPLICATION SPEC	RESTRICTED TO	
MATERIAL 		WEIGHT 114-19029	SCALE 5:1	
		CUSTOMER DRAWING	SHEET 1 OF 1	